

(19)



JAPANESE PATENT OFFICE

(3)

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 09116247 A

(43) Date of publication of application: 02.05.97 ✓

(51) Int. Cl.

H05K 1/16
H05K 3/46

(21) Application number: 07266874

(22) Date of filing: 16.10.95

(71) Applicant: OKI PURINTETSUDO CIRCUIT KK
OKI ELECTRIC IND CO LTD(72) Inventor: ITAYA SATORU
TAKAHASHI YOSHIRO
KARASUNO YUTAKA
NAKAKUKI MINORU

(54) MANUFACTURE OF CAPACITOR INCLUDING
BUILD UP TYPE PRINTED WIRING BOARD, ITS
PRINTED WIRING BOARD, AND MOUNTING
STRUCTURE OF CAPACITOR ON THE BOARD

part 108a and the capacitor upper part electrode 114 is
built in a board.

COPYRIGHT: (C)1997,JPO

(57) Abstract:

PROBLEM TO BE SOLVED: To attain easily compactly mounting a capacitor in a board at a low cost, by burying a capacitor part formed by curing paste for capacitor in an aperture part for mounting a capacitor, and forming a capacitor upper part electrode on the capacitor part.

SOLUTION: Paste for capacitor is injected in an aperture part for mounting a capacitor and cured by thermal treatment, and an insulating capacitor part 108a is formed. The upper part of resin 110 for insulating an upper and a lower conductor layers is eliminated by mechanical polishing like a buffing, and head parts of the buried capacitor part 108a and a post plating 109 are exposed in the same plane shape. Matching of capacitance is performed by adjusting the height of the capacitor part 108a, and an upper part conducting circuit 113 and a capacitor upper part electrode 114 are simultaneously formed. Thereby, a capacitor constituted of a capacitor lower part electrode 103, the capacitor

